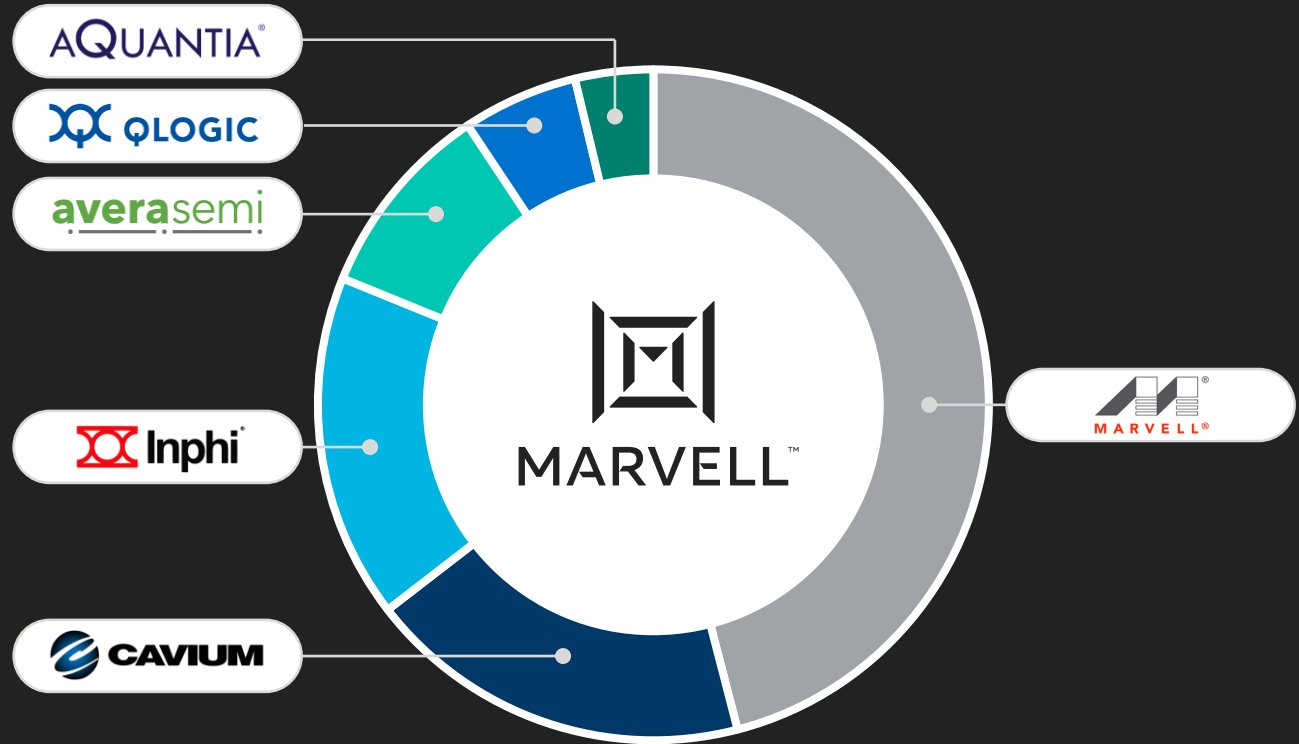


The New Marvell



Providing all the critical building blocks for data infrastructure

Industry Leading Data Infrastructure Product Lines

Compute

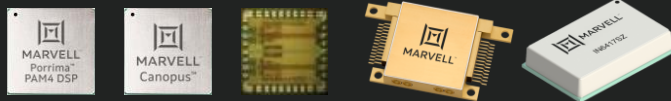


Security Solutions



Networking

High-speed Electro-Optics
PAM4 DSPs, Coherent DSPs, TIAs and Drivers



Ethernet
PHYs



Ethernet
switches



Silicon
photonics



Ethernet NICs



Automotive ethernet



Storage

HDD controllers and pre-amps



Flash SSD controllers
and NVMe accelerators



Fibre Channel HBAs



Custom ASICs

DC Connectivity Challenges

- System Requirements
 - Higher data rate in same or smaller form factor
 - Low cost. Low Power.
- Challenges
 - Power consumption / dissipation / thermal
 - Smaller footprint (volume) for components
 - Multiple process technologies (SiPho, SiGe, CMOS, GaAs, InP Laser)
 - Integrate at die level or packaging
 - Choose optimal process technology for the application
 - Helps power but more complex packaging
 - Advanced 2.5D / 3D packaging tooled for 12" wafers
 - Reliability

